MSFC ST12 requires the procurement of a custom Au sputtering target with the following specifications:

- 1.50” x 32.00” x 0.060” thick, Purity 99.99% (4N), Metallic Bonded to an OFHC Copper Backing Plate, 3.040” x 33.95” x 0.187” thick

Requirements:

- Fabrication of a gold (Au) sputtering target metallically bonded to copper backing plate for integration into a custom-built dual linear magnetron assembly
- Target and backing plate assembly must be vacuum and DC magnetron sputtering compatible
- Machine and assemble according to specifications above